



FIG. 7.22 Contact microsprings patterned into a 0.05 beryllium-copper sheet that is glued to a 1.6 mm FR4 or G-10 circuit board. (The number of contacts is much higher and the spacing much smaller than that shown in this simplified sketch.) Precise alignment between the test chip and contacts is provided by an alignment plate. The test chip is flipped upside down, dropped into the alignment frame, and pressed down against the microsprings with a spring-loaded pressure plate (not shown). (From Hamilton 1982.)